



*This certificate is granted and awarded by the authority of the Nadcap Management Council to:*

## **Benchmark Electronics (M) Sdn. Bhd.**

*Free Industrial Zone, Phase 1 Bayan Lepas, Pulau Pinang  
Penang, 11900  
Malaysia*

*This certificate demonstrates conformance and recognition of accreditation for specific services, as listed in [www.eAuditNet.com](http://www.eAuditNet.com) on the Qualified Manufacturers List (QML), to the revision in effect at the time of the audit for:*

## **Electronics**

Certificate Number: 11496184938

Expiration Date: 31 July 2020

Joseph G. Pinto

*Executive Vice President and Chief Operating Officer*



## SCOPE OF ACCREDITATION

### Electronics

#### **Benchmark Electronics (M) Sdn. Bhd.**

Free Industrial Zone, Phase 1 Bayan Lepas, Pulau Pinang  
Penang, 11900  
Malaysia

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: [www.eAuditNet.com](http://www.eAuditNet.com) - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

#### **AC7120 Rev E - Nadcap Audit Criteria for Circuit Card Assemblies (to be used on audits on/after 9 April 2017) (CANNOT BE COMBINED WITH AC7119 or AC7121)**

- 03–Company Information (mandatory)
- 04– General (mandatory)
- 05– Outsourced Processes (mandatory)
- 06– Process Control (mandatory)
- 07– Visual Acuity (mandatory)
- 08– Customer Data (mandatory)
- 09– Electrostatic Discharge (ESD) (mandatory)
- 10– Material Management (mandatory)
- 11– Moisture Sensitive Components and Materials
- 12– Kitting
- 13.1– In–Process Verification / Inspection: General (mandatory)
- 13.2– In–Process Verification / Inspection: Visual (mandatory)
- 13.3– In–Process Verification / Inspection: AOI
- 15– Cleanliness
- 16– Final Inspection (mandatory)
- 17– Rework (mandatory)

#### **AC7120/2 - General Soldering of Printed Board Assemblies (to be used on audits on/after 9 April 2017)**

- 03– General (mandatory)
- 05.1– Part Placement: General (mandatory)
- 05.2– Part Placement: Manual

08– Hand Soldering

**AC7120/3 - Plated Through Hole Technology (to be used on audits on/after 9 April 2017)**

04– Wave Soldering

**AC7120/4 - Surface Mount Technology (to be used on audits before 3 March 2019)**

04– Stencil Printing (mandatory)

05– Automated Part Placement (mandatory)

06– Reflow Soldering (mandatory)

**AC7120/6 - Lead Free Soldering (to be used on audits on/after 9 April 2017)**

03– Lead-Free Control Plan (LFCP) (mandatory)

04– Process Control (mandatory)

05– Training (mandatory)

**AC7120/7 - Conformal Coating of Printed Board Assemblies (to be used on audits on/after 9 April 2017)**

04– Material (mandatory)

05– Material and Equipment Compatibility (mandatory)

06– Preparation / Cleaning (mandatory)

07– Application / Drying / Curing (mandatory)

08– Thickness (mandatory)

09– Inspection (mandatory)

10– Rework (mandatory)

11– Training (mandatory)

**AC7120/9 - Programming (to be used on audits on/after 9 April 2017)**

04– General (mandatory)

05– Component Programming (Prior to Assembly)

**AC7120/10 - Final Testing (to be used on audits on/after 9 April 2017)**

04– General